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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
THOMAS W DYER	03/06/2008
HAINING S YANG	03/05/2008

RECEIVING PARTY DATA

Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	NEW ORCHARD ROAD
City:	ARMONK
State/Country:	NEW YORK
Postal Code:	10504

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12047376

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ATTORNEY DOCKET NUMBER:	FIS920080005US1
NAME OF SUBMITTER:	JOSEPH PETROKAITIS

Total Attachments: 1

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PATENT REEL: 020644 FRAME: 0010

Docket No.: FIS920080005US1

ASSIGNMENT

INVENTOR AND CITY	Whereas, we (1) Thomas W. Dyer, City of Pleasant Valley, County of Dutchess and State of New York;
	(2) Haining S. Yang, City of Wappingers Falls, County of Dutchess and State of New York;
	have invented certain improvements in
TITLE	SEMICONDUCTOR DEVICES HAVING TENSILE AND/OR COMPRESSIVE STRESS AND METHODS OF MANUFACTURING
DATES THAT	and executed, respectively, a United States patent application therefor on
INVENTORS SIGNED THE DECLARATION	(1) <u>3/06</u> , 2008, (2) <u>3/65</u> , 2008,
of husiness at	ERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and said application and invention, and to any United States and foreign patents to be obtained therefor;
hereby sell, as application and all rights o	for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, sign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said d invention therein disclosed for the United States and foreign countries, and in all foreign countries, if priority resulting from the filing of said United States application, and we request the
IBM, its succes	of Patents to issue any Letters Patent granted upon the inventions set forth in said application to ssors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said we will execute all papers necessary in connection with the United States and foreign applications bon to do so by IBM.

Signed and sealed

on 3/0,2008

RECORDED: 03/13/2008

PATENT REEL: 020644 FRAME: 0011